

Amendments to the Claims

1. (*Currently Amended*) A method of wedge-bonding wires in the manufacture of electronic devices, wherein:

[[·]] a reversible bonding tool is used having a wedge-bonding tip at opposite ends of the tool,

[[·]] and, after using the wedge-bonding tip at one end for bonding wires, the tool is reversed to use the wedge-bonding tip at the opposite end for bonding further wires.

2. (*Original*) A method according to Claim 1, wherein the bonding tool comprises a shank of tungsten carbide having the wedge-bonding tips at opposite ends of the shank.

3. (*Currently Amended*) A method ~~according to Claim 1 or Claim 2, according to Claim 1,~~ wherein the wires comprise ~~aluminium~~ aluminum or gold and are ultra-sonically bonded using a transducer coupled to the tool.

4. (*Original*) A wire-bonding machine for ultrasonic wedge-bonding of wires in the manufacture of electronic devices, wherein the machine includes a reversible bonding tool having a wedge-bonding tip at opposite ends of the tool, and a mount for coupling the tool to an ultrasonic transducer, the mount allowing the tool to be reversed so as to permit wire bonding using either the wedge-bonding tip at one end or the wedge-bonding tip at the opposite end.

5. (*Original*) A wire-bonding machine according to Claim 4, wherein the bonding tool comprises a shank having the wedge-bonding tips at opposite ends of the shank, and wherein the mount engages the tool at a position on the shank between its opposite ends.

6. (*Currently Amended*) A reversible bonding tool ~~for use in a method according to any one of Claims 1 to 3 or in a machine according to Claim 4 or Claim 5, wherein the tool comprises~~ comprising a shank having a wedge-bonding tip at opposite ends of the shank.

7. *(Currently Amended)* ~~A reversible bonding tool for use in a method according to any one of Claims 1 to 3 or in a machine according to Claim 4 or Claim 5, The reversible bonding tool as recited in Claim 6, wherein the tool comprises a~~ wherein the shank having includes at its opposite ends a material which is different to that of the shank and which provides a wedge-bonding tip at each of the opposite ends of the shank.
8. *(Currently Amended)* ~~A machine according to Claim 4 or Claim 5, The wire-bonding machine as recited in Claim 4, or a tool according to Claim 6 or Claim 7, wherein the~~ wedge-bonding tips at opposite ends are of tungsten carbide.
9. *(Currently Amended)* An electronic device, ~~for example an integrated circuit or a power semiconductor device, that includes having~~ connections in the form of wires which are wedge-bonded using ~~a method the method as recited in Claim 1, or machine or tool according to any one of the preceding Claims.~~
10. *(New)* An electronic device that includes connections in the form of wires which are wedge-bonded using the wire-bonding machine as recited in Claim 4.
11. *(New)* The reversible bonding tool as recited in Claim 6, wherein the wedge-bonding tips at opposite ends are of tungsten carbide.
12. *(New)* An electronic device that includes connections in the form of wires which are wedge-bonded using the reversible bonding tool as recited in Claim 6.